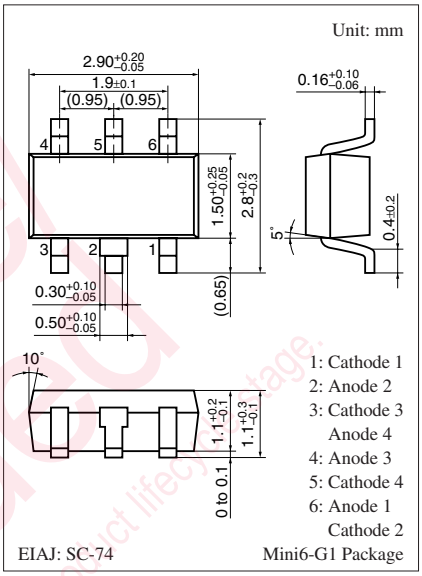
MA6X125 (MA125)

Silicon epitaxial planar type

For switching circuit

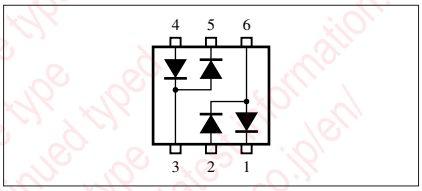
■ Features

- Four isolated elements contained in one package, allowing high-density mounting



Marking Symbol: M2I

Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

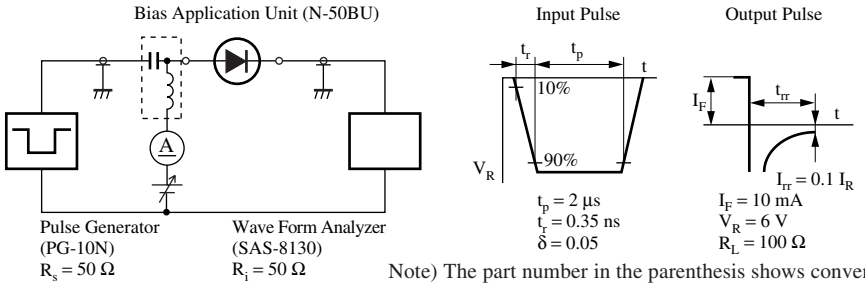
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current *	I_F	100	mA
Peak forward current *	I_{FM}	200	mA
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) ∗: Value for single diode

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

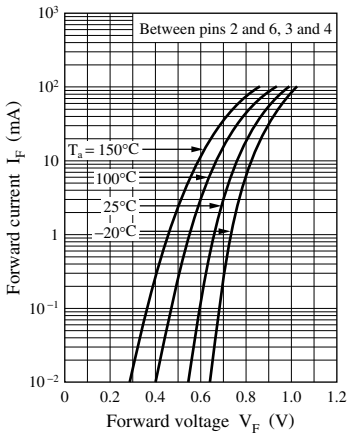
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.2	V
Reverse voltage	V_R	$I_R = 100$ µA	40			V
Reverse current	I_R	$V_R = 40$ V			100	nA
Terminal capacitance	C_t	$V_R = 0$ V, f = 1 MHz			5.0	pF
Reverse recovery time *3	t_{rr1} *1	$I_F = 10$ mA, $V_R = 6$ V		150		ns
	t_{rr2} *2	$I_{rr} = 0.1\ I_R$, $R_L = 100\ \Omega$		9		

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. ∗1: Between pins 1 and 6, Between pins 3 and 5
∗2: Between pins 2 and 6, Between pins 3 and 4
∗3: t_{rr} measurement circuit

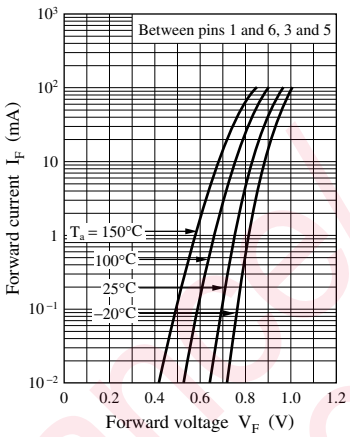


Note) The part number in the parenthesis shows conventional part number.

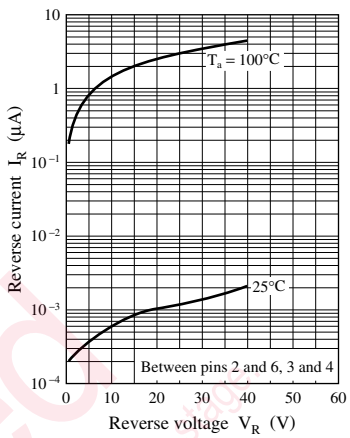
I_F — V_F



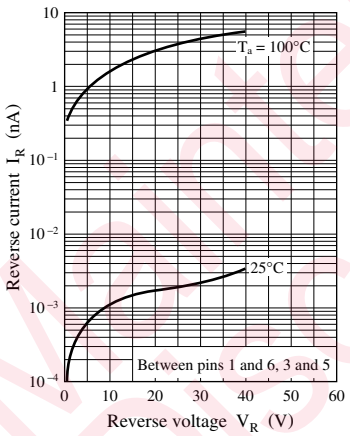
I_F — V_F



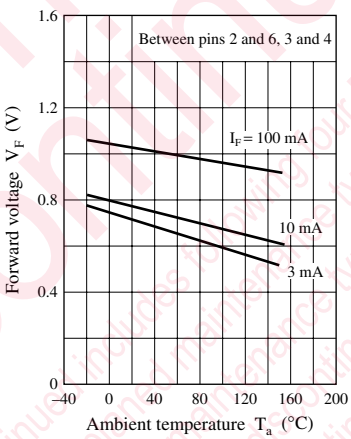
I_R — V_R



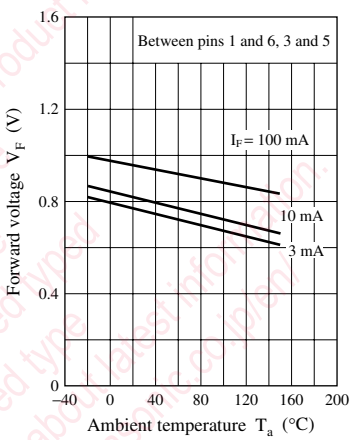
I_R — V_R



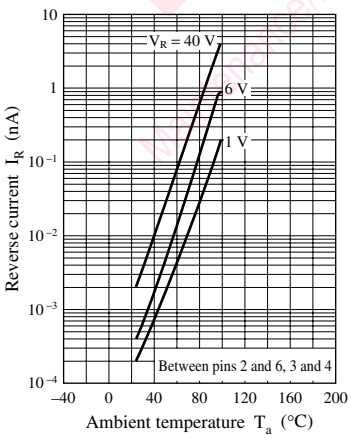
V_F — T_a



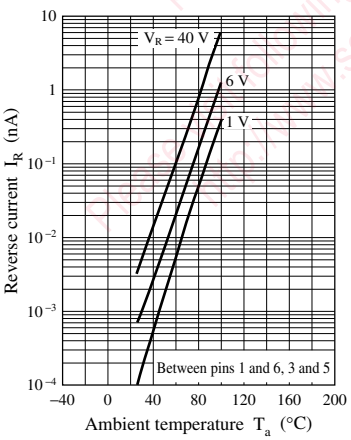
V_F — T_a



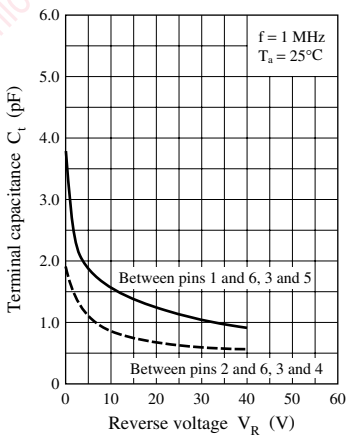
I_R — T_a



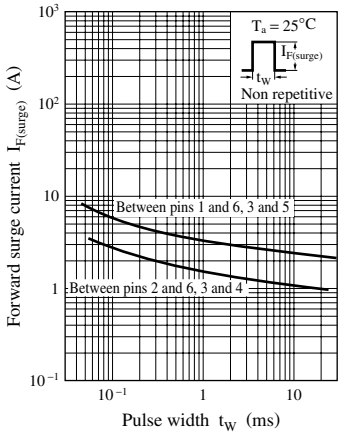
I_R — T_a



C_t — V_R



$I_{F(surge)}$ — t_W



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